

Abstract

An integrated circuit die comprises an internal signal pad arranged at a location away from a periphery of the die, a peripheral signal pad arranged proximate the periphery of the die, and a switch coupled between the internal signal pad and the peripheral signal pad. The switch is configurable in at least a first state in which the internal signal pad is not operatively connected to the peripheral signal pad, and a second state in which the internal signal pad is operatively connected to the peripheral signal pad, responsive to a control signal having one of respective first and second signal characteristics. The switch is configured in the first state during normal operation of the integrated circuit die, and is configured in the second state to permit test access to the internal signal pad via the peripheral signal pad.